| <b>Notification Number:</b>                                                                                                                            | 2016          | 0919                                        | 9001                 | Notification   | Date:           | September 20, 2016   |  |
|--------------------------------------------------------------------------------------------------------------------------------------------------------|---------------|---------------------------------------------|----------------------|----------------|-----------------|----------------------|--|
| Title: Datasheet for                                                                                                                                   | CDCE913-0     | Q1/C                                        | DCEL913-Q1           |                |                 |                      |  |
| <b>Customer Contact:</b>                                                                                                                               | PCN Manager   | <u>Anager</u> <b>Dept:</b> Quality Services |                      |                |                 |                      |  |
| Change Type:                                                                                                                                           |               |                                             |                      |                |                 |                      |  |
| Assembly Site                                                                                                                                          |               | Design                                      |                      |                | Wafer Bump Site |                      |  |
| Assembly Process                                                                                                                                       |               | $\boxtimes$                                 | Data Sheet           |                | _               | Wafer Bump Material  |  |
| Assembly Materials                                                                                                                                     |               | Щ                                           | Part number change   |                |                 | Wafer Bump Process   |  |
| Mechanical Specification                                                                                                                               |               |                                             | Test Site            |                |                 | ifer Fab Site        |  |
| Packing/Shipping/Labeling                                                                                                                              |               |                                             | Test Process         |                |                 | fer Fab Materials    |  |
|                                                                                                                                                        |               |                                             | Notification Details |                |                 | fer Fab Process      |  |
| Description of Change:                                                                                                                                 |               |                                             |                      |                |                 |                      |  |
| Texas Instruments Inco                                                                                                                                 |               | anno                                        | ouncing an infe      | ormation only  | notific         | ation                |  |
| The product datasheet(s                                                                                                                                |               |                                             |                      |                |                 |                      |  |
| The product databases                                                                                                                                  | o, io apaace  | u uo                                        |                      | iange revision |                 | -                    |  |
|                                                                                                                                                        |               |                                             |                      |                |                 | TEXAS<br>INSTRUMENTS |  |
| CDCE913-Q1, CDCEL913-Q                                                                                                                                 | 1             |                                             |                      |                |                 | INSTRUMENTS          |  |
|                                                                                                                                                        |               |                                             |                      |                |                 | www.ti.com           |  |
| Changes from Revision A (March 2010) to Revision B                                                                                                     |               |                                             |                      |                |                 | Page                 |  |
| Changes from Revision A (March 2010) to Revision B                                                                                                     |               |                                             |                      |                |                 |                      |  |
| Added Feature Description section, Device Functional Modes, Application and Implementation section, Power                                              |               |                                             |                      |                |                 |                      |  |
| Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section |               |                                             |                      |                |                 |                      |  |
| Changed ESD Ratings: Human-body model (HBM) from 2500 V to 2000 V and Charged-device model (CDM) from                                                  |               |                                             |                      |                |                 |                      |  |
| 500 V to 1000 V                                                                                                                                        |               |                                             |                      |                |                 | 5                    |  |
| Changed second S to Sr in Byte Read Protocol                                                                                                           |               |                                             |                      |                |                 | 15                   |  |
| The datasheet number will be changing.                                                                                                                 |               |                                             |                      |                |                 |                      |  |
| Device Family                                                                                                                                          | wiii be chan  | ging                                        | . Change Froi        | m:             | Chan            | ge To:               |  |
| CDCE913-Q1/CDCEL91                                                                                                                                     | I3-∩1         |                                             | SCAS918A             | 11.            |                 |                      |  |
|                                                                                                                                                        |               |                                             |                      |                |                 |                      |  |
| These changes may be reviewed at the datasheet links provided.  http://www.ti.com/lit/ds/symlink/cdce913-q1.pdf                                        |               |                                             |                      |                |                 |                      |  |
| http://www.ti.com/lit/d                                                                                                                                | s/symlink/co  | dce9                                        | <u>13-q1.pdf</u>     |                |                 |                      |  |
| Reason for Change:                                                                                                                                     |               |                                             |                      |                |                 |                      |  |
| To more accurately refle                                                                                                                               | ect device cl | hara                                        | cteristics.          |                |                 |                      |  |
| Anticipated impact or                                                                                                                                  | n Fit, Form   | , Fu                                        | nction, Quali        | ty or Reliabi  | lity (p         | ositive / negative): |  |
| No anticipated impact. To the actual device                                                                                                            | Γhis is a spe | cific                                       | ation change a       | announcement   | t only.         | There are no changes |  |
| Changes to product identification resulting from this notification:                                                                                    |               |                                             |                      |                |                 |                      |  |
| None.                                                                                                                                                  |               |                                             |                      |                |                 |                      |  |
| Product Affected:                                                                                                                                      |               |                                             |                      |                |                 |                      |  |
| CDCE913QPWRQ1 CDCEL913IPWRQ1                                                                                                                           |               |                                             |                      |                |                 |                      |  |
|                                                                                                                                                        |               |                                             | 1 -                  |                |                 |                      |  |

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| or your local freid Sales Representative. |                                |  |  |
|-------------------------------------------|--------------------------------|--|--|
| Location                                  | E-Mail                         |  |  |
| USA                                       | PCNAmericasContact@list.ti.com |  |  |
| Europe                                    | PCNEuropeContact@list.ti.com   |  |  |
| Asia Pacific                              | PCNAsiaContact@list.ti.com     |  |  |
| Japan                                     | PCNJapanContact@list.ti.com    |  |  |